

ABSTRACT

Provided is a heat sink unit that is less likely to damage a package and has excellent handleability. The heat sink unit 1 includes a base 90, a cover 20, a first lever 80, a third lever 50, and a heat sink 30. The first lever 80 is rotatably held by the base 90, carries the heat sink 30 and a heat sink pedestal 40, and is hard stopped at the base 90 by an end portion of the first lever 80. The third lever 50 is rotatably held by the cover 20, is connected to the first lever 80 to open and close the same, and controls up-and-down movements of the heat sink pedestal 40 by a tip end of the third lever 50. The heat sink 30 is configured to press the IC package 100 with timing shifted by a long hole of the third lever 50 after the first lever 80 is hard stopped at the base 90,

<Figure 1>